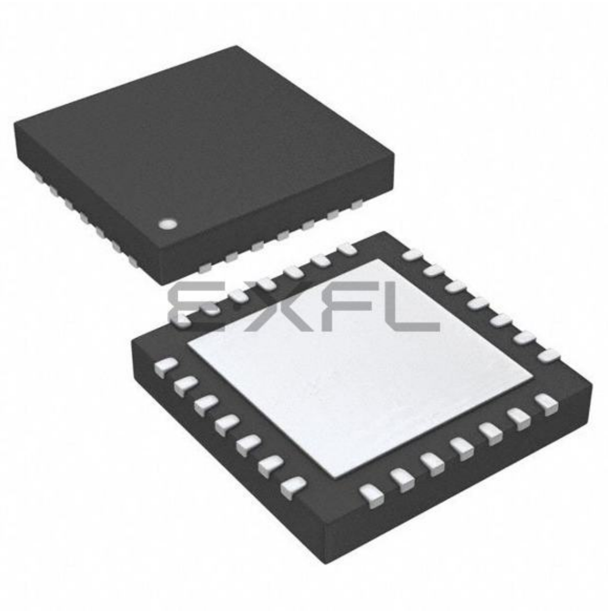

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Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	21
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx130f064bt-i-ml

TABLE 8: PIN NAMES FOR 36-PIN USB DEVICES

36-PIN VTLA (TOP VIEW)(1,2,3,5)

PIC32MX210F016C
PIC32MX220F032C
PIC32MX230F064C
PIC32MX250F128C

36

1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/PMD2/RB2	19	TDO/RPB9/SDA1/CTED4/PMD3/RB9
2	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/PMWR/RB3	20	RPC9/CTED7/RC9
3	PGED4(4)/AN6/RPC0/RC0	21	VSS
4	PGEC4(4)/AN7/RPC1/RC1	22	VCAP
5	VDD	23	VDD
6	VSS	24	PGED2/RPB10/D+/CTED11/RB10
7	OSC1/CLKI/RPA2/RA2	25	PGEC2/RPB11/D-/RB11
8	OSC2/CLKO/RPA3/PMA0/RA3	26	VUSB3V3
9	SOSCI/RPB4/RB4	27	AN11/RPB13/CTPLS/PMRD/RB13
10	SOSCO/RPA4/T1CK/CTED9/PMA1/RA4	28	CVREFOUT/AN10/C3INB/RPB14/VBUSON/SCK1/CTED5/RB14
11	AN12/RPC3/RC3	29	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15
12	VSS	30	AVSS
13	VDD	31	AVDD
14	VDD	32	$\overline{\text{MCLR}}$
15	TMS/RPB5/USBID/RB5	33	PGED3/VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/PMD7/RA0
16	VBUS	34	PGEC3/VREF-/CVREF-/AN1/RPA1/CTED2/PMD6/RA1
17	TDI/RPB7/CTED3/PMD5/INT0/RB7	35	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/PMD0/RB0
18	TCK/RPB8/SCL1/CTED10/PMD4/RB8	36	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/PMD1/RB1

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 “Peripheral Pin Select”** for restrictions.
2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 “I/O Ports”** for more information.
3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.
4: This pin function is not available on PIC32MX210F016C and PIC32MX120F032C devices.
5: Shaded pins are 5V tolerant.

REGISTER 5-4: NVMDATA: FLASH PROGRAM DATA REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<7:0>							

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-0 **NVMDATA<31:0>:** Flash Programming Data bits

Note: The bits in this register are only reset by a Power-on Reset (POR).

REGISTER 5-5: NVMSRCADDR: SOURCE DATA ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<7:0>							

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-0 **NVMSRCADDR<31:0>:** Source Data Address bits

The system physical address of the data to be programmed into the Flash when the NVMOP<3:0> bits (NVMCON<3:0>) are set to perform row programming.

REGISTER 9-4: DCRCCON: DMA CRC CONTROL REGISTER (CONTINUED)

bit 6 **CRCAPP:** CRC Append Mode bit[1]

`1` = The DMA transfers data from the source into the CRC but NOT to the destination. When a block transfer completes the DMA writes the calculated CRC value to the location given by CHxDSA

`0` = The DMA transfers data from the source through the CRC obeying WBO as it writes the data to the destination

bit 5 **CRCTYP:** CRC Type Selection bit

`1` = The CRC module will calculate an IP header checksum
`0` = The CRC module will calculate a LFSR CRC

bit 4-3 **Unimplemented:** Read as ‘`0`’

bit 2-0 **CRCCH<2:0>:** CRC Channel Select bits

`111` = CRC is assigned to Channel 7
`110` = CRC is assigned to Channel 6
`101` = CRC is assigned to Channel 5
`100` = CRC is assigned to Channel 4
`011` = CRC is assigned to Channel 3
`010` = CRC is assigned to Channel 2
`001` = CRC is assigned to Channel 1
`000` = CRC is assigned to Channel 0

Note 1: When WBO = `1`, unaligned transfers are not supported and the CRCAPP bit cannot be set.

NOTES:

REGISTER 10-1: U1OTGIR: USB OTG INTERRUPT STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	U-0	R/WC-0, HS
	IDIF	T1MSECIF	LSTATEIF	ACTVIF	SESVDIF	SESENDIF	—	VBUSVDIF

Legend:	WC = Write ‘1’ to clear	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as ‘0’

bit 7 **IDIF:** ID State Change Indicator bit

1 = A change in the ID state was detected
0 = No change in the ID state was detected

bit 6 **T1MSECIF:** 1 Millisecond Timer bit

1 = 1 millisecond timer has expired
0 = 1 millisecond timer has not expired

bit 5 **LSTATEIF:** Line State Stable Indicator bit

1 = USB line state has been stable for 1 ms, but different from last time
0 = USB line state has not been stable for 1 ms

bit 4 **ACTVIF:** Bus Activity Indicator bit

1 = Activity on the D+, D-, ID or VBUS pins has caused the device to wake-up
0 = Activity has not been detected

bit 3 **SESVDIF:** Session Valid Change Indicator bit

1 = VBUS voltage has dropped below the session end level
0 = VBUS voltage has not dropped below the session end level

bit 2 **SESENDIF:** B-Device VBUS Change Indicator bit

1 = A change on the session end input was detected
0 = No change on the session end input was detected

bit 1 **Unimplemented:** Read as ‘0’

bit 0 **VBUSVDIF:** A-Device VBUS Change Indicator bit

1 = A change on the session valid input was detected
0 = No change on the session valid input was detected

REGISTER 10-5: U1PWRC: USB POWER CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R-0	U-0	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
	UACTPND	—	—	USLPGRD	USBBUSY(1)	—	USUSPEND	USBPWR

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as ‘`0`’

bit 7 **UACTPND:** USB Activity Pending bit

`1` = USB bus activity has been detected; however, an interrupt is pending, which has yet to be generated
`0` = An interrupt is not pending

bit 6-5 **Unimplemented:** Read as ‘`0`’

bit 4 **USLPGRD:** USB Sleep Entry Guard bit

`1` = Sleep entry is blocked if USB bus activity is detected or if a notification is pending
`0` = USB module does not block Sleep entry

bit 3 **USBBUSY:** USB Module Busy bit(1)

`1` = USB module is active or disabled, but not ready to be enabled

`0` = USB module is not active and is ready to be enabled

bit 2 **Unimplemented:** Read as ‘`0`’

bit 1 **USUSPEND:** USB Suspend Mode bit

`1` = USB module is placed in Suspend mode
(The 48 MHz USB clock will be gated off. The transceiver is placed in a low-power state.)
`0` = USB module operates normally

bit 0 **USBPWR:** USB Operation Enable bit

`1` = USB module is turned on
`0` = USB module is disabled
(Outputs held inactive, device pins not used by USB, analog features are shut down to reduce power consumption.)

Note 1: When USBPWR = `0` and USBBUSY = `1`, status from all other registers is invalid and writes to all USB module registers produce undefined results.

REGISTER 10-11: U1CON: USB CONTROL REGISTER (CONTINUED)

bit 1 **PPBRST:** Ping-Pong Buffers Reset bit

`1` = Reset all Even/Odd buffer pointers to the EVEN Buffer Descriptor banks
`0` = Even/Odd buffer pointers are not Reset

bit 0 **USBEN:** USB Module Enable bit(4)

`1` = USB module and supporting circuitry is enabled
`0` = USB module and supporting circuitry is disabled

SOFEN: SOF Enable bit(5)

`1` = SOF token is sent every 1 ms
`0` = SOF token is disabled

Note 1: Software is required to check this bit before issuing another token command to the U1TOK register (see Register 10-15).

2: All host control logic is reset any time that the value of this bit is toggled.

3: Software must set RESUME for 10 ms if the part is a function, or for 25 ms if the part is a host, and then clear it to enable remote wake-up. In Host mode, the USB module will append a Low-Speed EOP to the RESUME signaling when this bit is cleared.

4: Device mode.

5: Host mode.

TABLE 11-6: PERIPHERAL PIN SELECT INPUT REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
FA04	INT1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	INT1R<3:0>				0000
FA08	INT2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	INT2R<3:0>				0000
FA0C	INT3R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	INT3R<3:0>				0000
FA10	INT4R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	INT4R<3:0>				0000
FA18	T2CKR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	T2CKR<3:0>				0000
FA1C	T3CKR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	T3CKR<3:0>				0000
FA20	T4CKR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	T4CKR<3:0>				0000
FA24	T5CKR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	T5CKR<3:0>				0000
FA28	IC1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	IC1R<3:0>				0000
FA2C	IC2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	IC2R<3:0>				0000
FA30	IC3R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	IC3R<3:0>				0000
FA34	IC4R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	IC4R<3:0>				0000
FA38	IC5R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	IC5R<3:0>				0000
FA48	OCFAR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	OCFAR<3:0>				0000
FA4C	OCFBR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	OCFBR<3:0>				0000
FA50	U1RXR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U1RXR<3:0>				0000

TABLE 11-7: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
FB8C	RPC8R[1]	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPC8<3:0>				0000
FB90	RPC9R[3]	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPC9<3:0>				0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: This register is only available on 44-pin devices.

2: This register is only available on PIC32MX1XX devices.

3: This register is only available on 36-pin and 44-pin devices.

NOTES:

REGISTER 20-1: PMCON: PARALLEL PORT CONTROL REGISTER (CONTINUED)

bit 4 **Unimplemented:** Read as ‘`0`’

bit 3 **CS1P:** Chip Select 0 Polarity bit(2)
`1` = Active-high (PMCS1)
`0` = Active-low ($\overline{\text{PMCS1}}$)

bit 2 **Unimplemented:** Read as ‘`0`’

bit 1 **WRSP:** Write Strobe Polarity bit

For Slave Modes and Master mode 2 (MODE<1:0> = `00`,`01`,`10`):
`1` = Write strobe active-high (PMWR)
`0` = Write strobe active-low ($\overline{\text{PMWR}}$)

For Master mode 1 (MODE<1:0> = `11`):
`1` = Enable strobe active-high (PMENB)
`0` = Enable strobe active-low ($\overline{\text{PMENB}}$)

bit 0 **RDSP:** Read Strobe Polarity bit

For Slave modes and Master mode 2 (MODE<1:0> = `00`,`01`,`10`):
`1` = Read Strobe active-high (PMRD)
`0` = Read Strobe active-low ($\overline{\text{PMRD}}$)

For Master mode 1 (MODE<1:0> = `11`):
`1` = Read/write strobe active-high (PMRD/$\overline{\text{PMWR}}$)
`0` = Read/write strobe active-low ($\overline{\text{PMRD}}$/PMWR)

Note 1: When using 1:1 PBCLK divisor, the user’s software should not read/write the peripheral’s SFRs in the SYSCLK cycle immediately following the instruction that clears the module’s ON control bit.

2: These bits have no effect when their corresponding pins are used as address lines.

REGISTER 21-1: RTCCON: RTC CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
	—	—	—	—	—	—	CAL<9:8>	
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CAL<7:0>							
15:8	R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	ON(1,2)	—	SIDL	—	—	—	—	—
7:0	R/W-0	R-0	U-0	U-0	R/W-0	R-0	R-0	R/W-0
	RTSECSEL(3)	RTCCLKON	—	—	RTCWREN(4)	RTCSYNC	HALFSEC(5)	RTCOE

Legend:
R = Readable bit W = Writable bit U = Unimplemented bit, read as ‘0’
-n = Value at POR ‘1’ = Bit is set ‘0’ = Bit is cleared x = Bit is unknown

bit 31-26 **Unimplemented:** Read as ‘0’

bit 25-16 **CAL<9:0>:** RTC Drift Calibration bits, which contain a signed 10-bit integer value
0111111111 = Maximum positive adjustment, adds 511 RTC clock pulses every one minute
•
•
•
0000000001 = Minimum positive adjustment, adds 1 RTC clock pulse every one minute
0000000000 = No adjustment
1111111111 = Minimum negative adjustment, subtracts 1 RTC clock pulse every one minute
•
•
•
1000000000 = Maximum negative adjustment, subtracts 512 clock pulses every one minute

bit 15 **ON:** RTCC On bit(1,2)
1 = RTCC module is enabled
0 = RTCC module is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **SIDL:** Stop in Idle Mode bit
1 = Disables the PBCLK to the RTCC when the device enters Idle mode
0 = Continue normal operation when the device enters Idle mode

bit 12-8 **Unimplemented:** Read as ‘0’

bit 7 **RTSECSEL:** RTCC Seconds Clock Output Select bit(3)
1 = RTCC Seconds Clock is selected for the RTCC pin
0 = RTCC Alarm Pulse is selected for the RTCC pin

bit 6 **RTCCLKON:** RTCC Clock Enable Status bit
1 = RTCC Clock is actively running
0 = RTCC Clock is not running

Note 1: The ON bit is only writable when RTCWREN = 1.
2: When using the 1:1 PBCLK divisor, the user’s software should not read/write the peripheral’s SFRs in the SYSCLK cycle immediately following the instruction that clears the module’s ON bit.
3: Requires RTCOE = 1 (RTCCON<0>) for the output to be active.
4: The RTCWREN bit can be set only when the write sequence is enabled.
5: This bit is read-only. It is cleared to ‘0’ on a write to the seconds bit fields (RTCTIME<14:8>).

Note: This register is reset only on a Power-on Reset (POR).

The processor will exit, or ‘wake-up’, from Sleep on one of the following events:

- On any interrupt from an enabled source that is operating in Sleep. The interrupt priority must be greater than the current CPU priority.
- On any form of device Reset
- On a WDT time-out

If the interrupt priority is lower than or equal to the current priority, the CPU will remain Halted, but the PBCLK will start running and the device will enter into Idle mode.

26.3.2 IDLE MODE

In Idle mode, the CPU is Halted but the System Clock (SYSCLK) source is still enabled. This allows peripherals to continue operation when the CPU is Halted. Peripherals can be individually configured to Halt when entering Idle by setting their respective SIDL bit. Latency, when exiting Idle mode, is very low due to the CPU oscillator source remaining active.

> **Note 1:** Changing the PBCLK divider ratio requires recalculation of peripheral timing. For example, assume the UART is configured for 9600 baud with a PB clock ratio of 1:1 and a POSC of 8 MHz. When the PB clock divisor of 1:2 is used, the input frequency to the baud clock is cut in half; therefore, the baud rate is reduced to 1/2 its former value. Due to numeric truncation in calculations (such as the baud rate divisor), the actual baud rate may be a tiny percentage different than expected. For this reason, any timing calculation required for a peripheral should be performed with the new PB clock frequency instead of scaling the previous value based on a change in the PB divisor ratio.
>
> **2:** Oscillator start-up and PLL lock delays are applied when switching to a clock source that was disabled and that uses a crystal and/or the PLL. For example, assume the clock source is switched from POSC to LPRC just prior to entering Sleep in order to save power. No oscillator start-up delay would be applied when exiting Idle. However, when switching back to POSC, the appropriate PLL and/or oscillator start-up/lock delays would be applied.

The device enters Idle mode when the SLPEN (OSCCON<4>) bit is clear and a `WAIT` instruction is executed.

The processor will wake or exit from Idle mode on the following events:

- On any interrupt event for which the interrupt source is enabled. The priority of the interrupt event must be greater than the current priority of the CPU. If the priority of the interrupt event is lower than or equal to current priority of the CPU, the CPU will remain Halted and the device will remain in Idle mode.
- On any form of device Reset
- On a WDT time-out interrupt

26.3.3 PERIPHERAL BUS SCALING METHOD

Most of the peripherals on the device are clocked using the PBCLK. The Peripheral Bus can be scaled relative to the SYSCLK to minimize the dynamic power consumed by the peripherals. The PBCLK divisor is controlled by PBDIV<1:0> (OSCCON<20:19>), allowing SYSCLK to PBCLK ratios of 1:1, 1:2, 1:4 and 1:8. All peripherals using PBCLK are affected when the divisor is changed. Peripherals such as the USB, Interrupt Controller, DMA, and the bus matrix are clocked directly from SYSCLK. As a result, they are not affected by PBCLK divisor changes.

Changing the PBCLK divisor affects:

- The CPU to peripheral access latency. The CPU has to wait for next PBCLK edge for a read to complete. In 1:8 mode, this results in a latency of one to seven SYSCLKs.
- The power consumption of the peripherals. Power consumption is directly proportional to the frequency at which the peripherals are clocked. The greater the divisor, the lower the power consumed by the peripherals.

To minimize dynamic power, the PB divisor should be chosen to run the peripherals at the lowest frequency that provides acceptable system performance. When selecting a PBCLK divider, peripheral clock requirements, such as baud rate accuracy, should be taken into account. For example, the UART peripheral may not be able to achieve all baud rate values at some PBCLK divider depending on the SYSCLK value.

TABLE 30-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
Param. No.	**Typical$^{(2)}$**	**Max.**	**Units**	**Conditions**	
Power-Down Current (IPD) (Notes 1, 5)					
DC40k	44	70	µA	-40°C	Base Power-Down Current
DC40l	44	70	µA	+25°C	
DC40n	168	259	µA	+85°C	
DC40m	335	536	µA	+105ºC	
Module Differential Current					
DC41e	5	20	µA	3.6V	Watchdog Timer Current: ΔIWDT **(Note 3)**
DC42e	23	50	µA	3.6V	RTCC + Timer1 w/32 kHz Crystal: ΔIRTCC **(Note 3)**
DC43d	1000	1100	µA	3.6V	ADC: ΔIADC **(Notes 3,4)**

Note 1: The test conditions for IPD current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, and SRAM data memory Wait states = `1`
- No peripheral modules are operating, (ON bit = `0`), but the associated PMD bit is set
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD
- RTCC and JTAG are disabled

2: Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: IPD electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

TABLE 30-9: DC CHARACTERISTICS: I/O PIN INPUT INJECTION CURRENT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typ.[1]**	**Max.**	**Units**	**Conditions**
DI60a	I_{ICL}	**Input Low Injection Current**	0	—	-5[2,5]	mA	This parameter applies to all pins, with the exception of the power pins.
DI60b	I_{ICH}	**Input High Injection Current**	0	—	+5[3,4,5]	mA	This parameter applies to all pins, with the exception of all 5V tolerant pins, and the SOSCI, SOSCO, OSC1, D+, and D- pins.
DI60c	$\sum I_{ICT}$	**Total Input Injection Current (sum of all I/O and Control pins)**	-20[6]	—	+20[6]	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins (| I_{ICL} + | I_{ICH} |) ≤ $\sum I_{ICT}$)

Note 1: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: V_{IL} source < (V_{SS} - 0.3). Characterized but not tested.

3: V_{IH} source > (V_{DD} + 0.3) for non-5V tolerant pins only.

4: Digital 5V tolerant pins do not have an internal high side diode to V_{DD}, and therefore, cannot tolerate any "positive" input injection current.

5: Injection currents > | 0 | can affect the ADC results by approximately 4 to 6 counts (i.e., V_{IH} Source > (V_{DD} + 0.3) or V_{IL} source < (V_{SS} - 0.3)).

6: Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. If **Note 2**, I_{ICL} = (((Vss - 0.3) - V_{IL} source) / Rs). If **Note 3**, I_{ICH} = ((I_{ICH} source - (V_{DD} + 0.3)) / RS). RS = Resistance between input source voltage and device pin. If (V_{SS} - 0.3) ≤ V_{SOURCE} ≤ (V_{DD} + 0.3), injection current = `0`.

FIGURE 30-13: SPIx MODULE SLAVE MODE (CKE = 1) TIMING CHARACTERISTICS

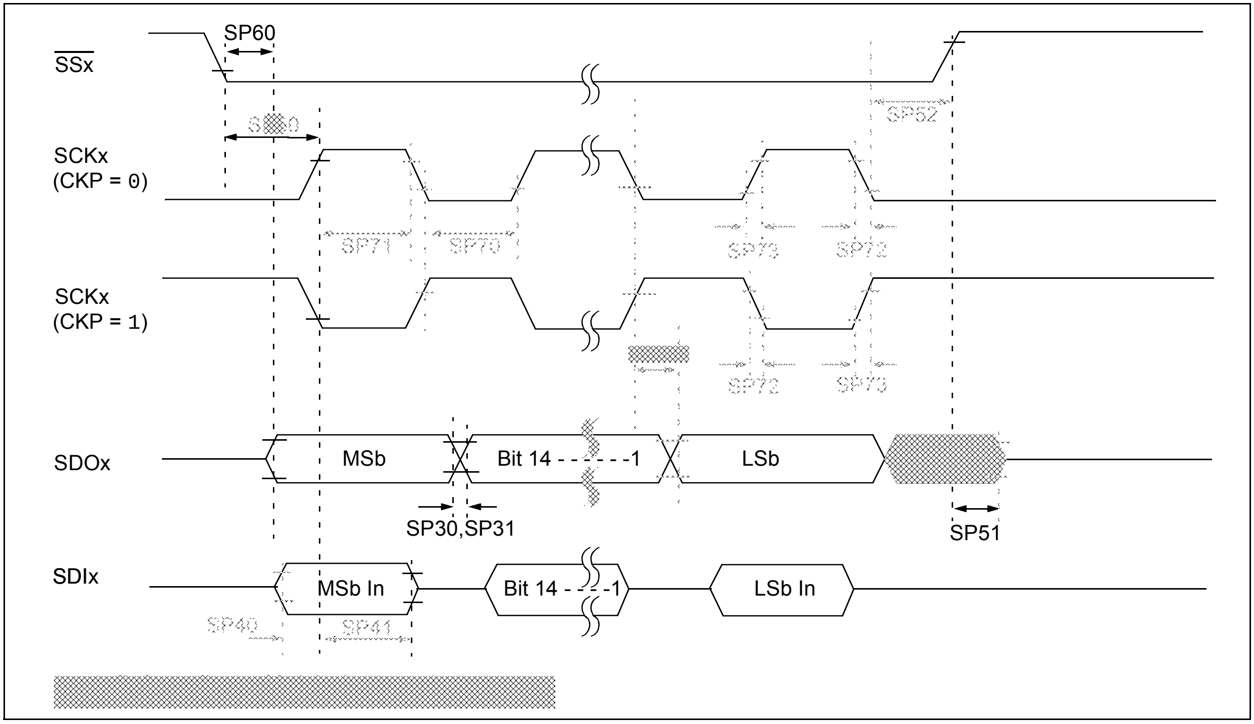


TABLE 30-31: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SP70	TSCL	SCKx Input Low Time **(Note 3)**	TSCK/2	—	—	ns	—
SP71	TSCH	SCKx Input High Time **(Note 3)**	TSCK/2	—	—	ns	—
SP72	TSCF	SCKx Input Fall Time	—	5	10	ns	—
SP73	TSCR	SCKx Input Rise Time	—	5	10	ns	—
SP30	TDOF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TDOR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TSCH2DOV, TSCL2DOV	SDOx Data Output Valid after SCKx Edge	—	—	20	ns	VDD > 2.7V
			—	—	30	ns	VDD < 2.7V
SP40	TDIV2SCH, TDIV2SCL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TSCH2DIL, TSCL2DIL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TSSL2SCH, TSSL2SCL	SSx ↓ to SCKx ↓ or SCKx ↑ Input	175	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 50 ns.

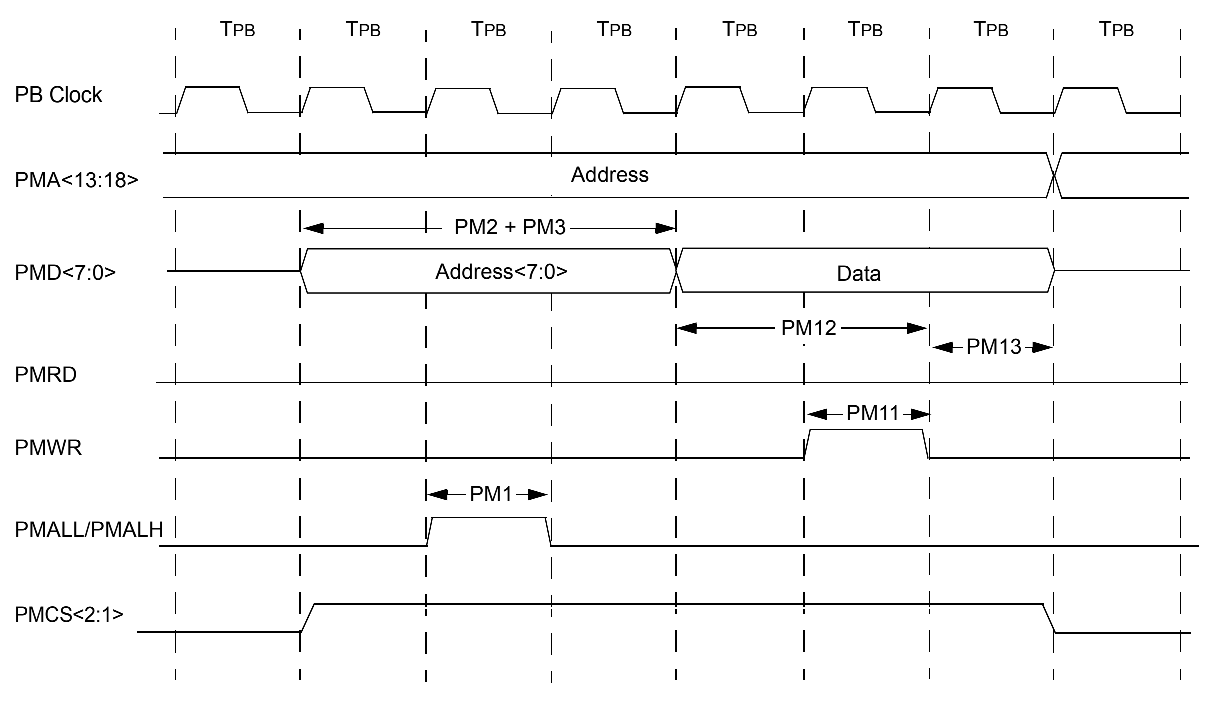
4: Assumes 50 pF load on all SPIx pins.

TABLE 30-38: PARALLEL MASTER PORT READ TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
PM1	TLAT	PMALL/PMALH Pulse Width	—	1 TPB	—	—	—
PM2	TADSU	Address Out Valid to PMALL/PMALH Invalid (address setup time)	—	2 TPB	—	—	—
PM3	TADHOLD	PMALL/PMALH Invalid to Address Out Invalid (address hold time)	—	1 TPB	—	—	—
PM4	TAHOLD	PMRD Inactive to Address Out Invalid (address hold time)	5	—	—	ns	—
PM5	TRD	PMRD Pulse Width	—	1 TPB	—	—	—
PM6	TDSU	PMRD or PMENB Active to Data In Valid (data setup time)	15	—	—	ns	—
PM7	TDHOLD	PMRD or PMENB Inactive to Data In Invalid (data hold time)	—	80	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 30-22: PARALLEL MASTER PORT WRITE TIMING DIAGRAM

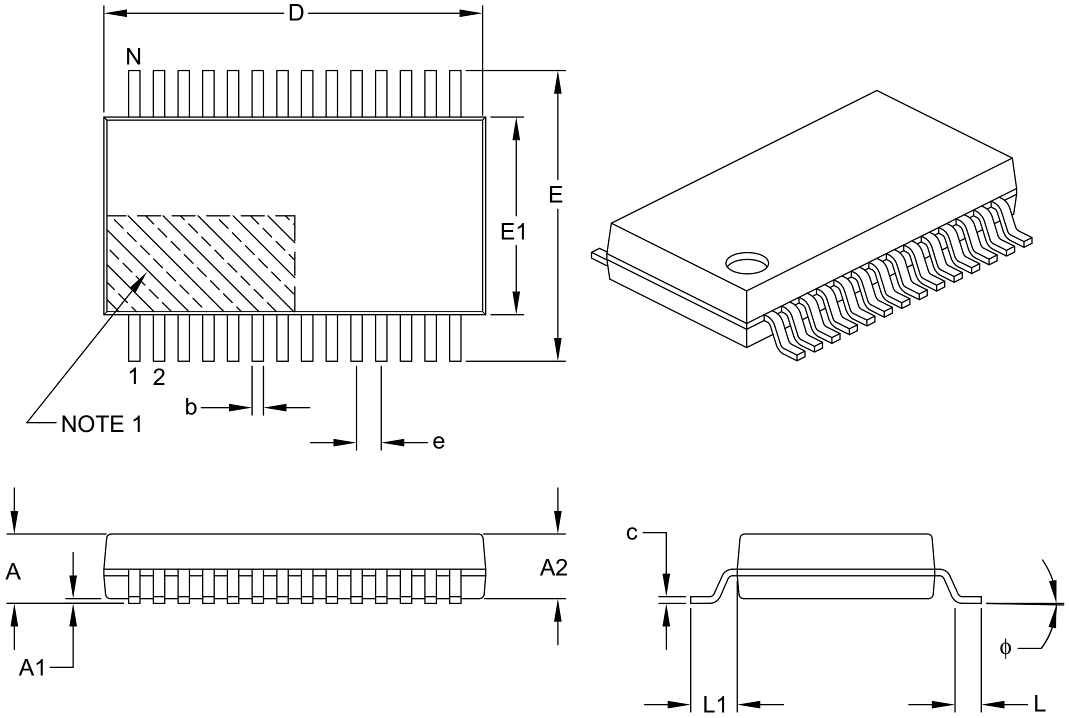


33.2 Package Details

This section provides the technical details of the packages.

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1	1.25 REF		
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

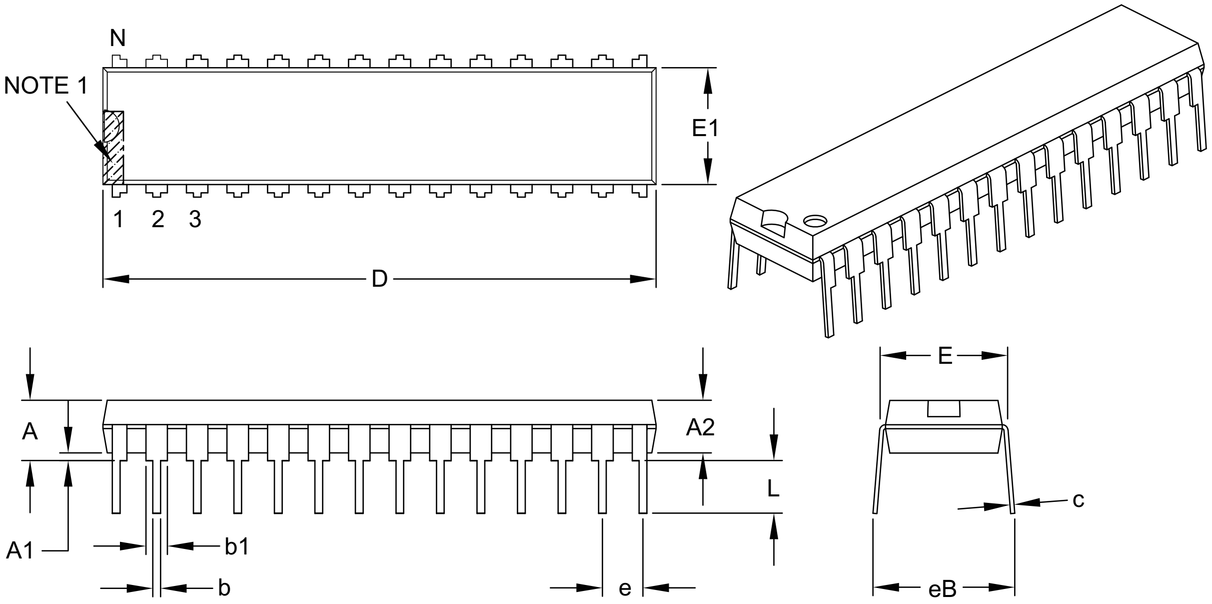
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

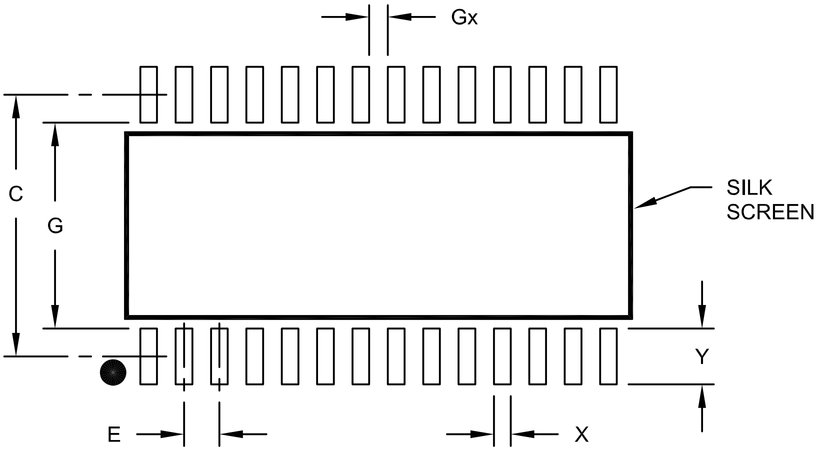
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A